



## **A New Era Begins for AMICRA and ASM Pacific Technology**

### **ASM Pacific Technology Acquires Amicra to Enter the Photonics Market**

Singapore and Hong Kong, April 3rd, 2018 - ASM Pacific Technology Ltd. ("ASMPT") announced that it has completed its acquisition of 100% of the shares of AMICRA Microtechnologies GmbH ("Amicra"). Amicra is a leading supplier of high precision die bonder for the photonics and advanced packaging market. The transaction which completed on April 4th 2018 will bring about a strengthened business, well-placed to serve not only the fast growing Silicon Photonics assembly equipment market but also the wider high precision flip chip and die bonding markets.

Headquartered in Singapore and listed in the Hong Kong Stock Exchange, ASMPT is the world's largest back-end semiconductor equipment supplier and SMT Solutions provider.

"We are excited about this strategic investment," said Mr. Lee Wai Kwong, CEO of ASM Pacific Technology. "Amicra's sub-micron high accuracy die bonder is complementary to the Group's existing product portfolio. Amicra has a leading position in the photonics market which the Group believes is of high growth potential. I am confident that this combination will further strengthen our future growth opportunities and help to deliver even higher value-add to our customers."

"Following our increasing penetration of markets for high precision die attach, especially in the rapidly growing area of Silicon Photonics manufacturing, it makes a lot of sense to merge with a strong strategic partner to better support our growing international customers base. With their scale and established international supply chain, sales channel and customers support capability, the merger with ASMPT will allow us to take next steps in the further development of our business. I am happy for Amicra and our customers and I am excited about the opportunity to work with the ASMPT" says Mr Rudolf Kaiser, managing director of Amicra.